

CMLD6263DO

SURFACE MOUNT SILICON
DUAL OPPOSING
HIGH VOLTAGE
SCHOTTKY DIODE



SOT-563 CASE



www.centralemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMLD6263DO incorporates two galvanically isolated, high voltage, low V_F silicon diodes with an opposing Anode/Cathode configuration, in a space saving SOT-563 surface mount package. These diodes are designed for fast switching applications requiring a low forward voltage drop.

MARKING CODE: 630

FEATURES:

- Dual Opposing (DO) Schottky Diodes
- High Voltage (70V)
- Low Forward Voltage
- Galvanically Isolated

MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$)

Peak Repetitive Reverse Voltage

Continuous Forward Current

Peak Forward Surge Current, $t_p=1.0\text{s}$

Power Dissipation

Operating and Storage Junction Temperature

Thermal Resistance

SYMBOL

V_{RRM}

I_F

I_{FSM}

P_D

T_J, T_{stg}

θ_{JA}

70

15

50

250

-65 to +150

500

UNITS

V

mA

mA

mW

$^\circ\text{C}$

$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS PER DIODE: ($T_A=25^\circ\text{C}$ unless otherwise noted)

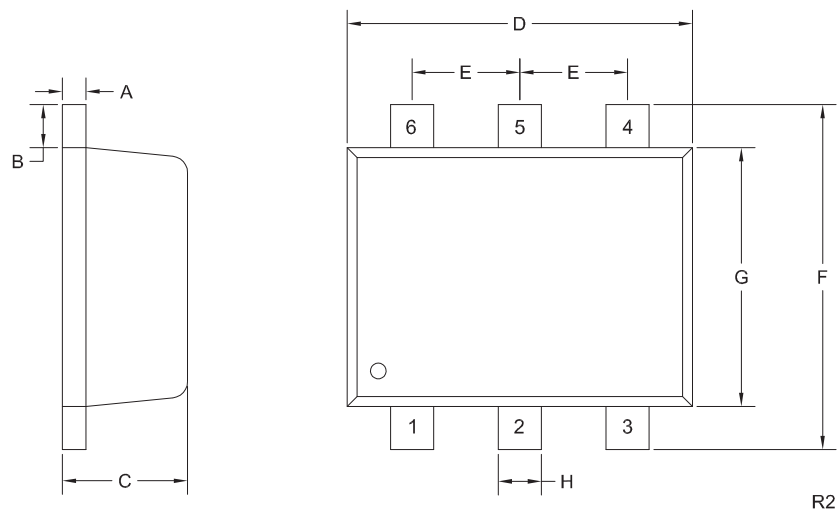
SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_R	$V_R=50\text{V}$		98	200	nA
BV_R	$I_R=10\mu\text{A}$	70			V
V_F	$I_F=1.0\text{mA}$		395	410	mV
C_J	$V_R=0, f=1.0\text{MHz}$			2.0	pF
t_{rr}	$I_R=I_F=10\text{mA}, I_{rr}=1.0\text{mA}, R_L=100\Omega$			5.0	ns

R5 (15-June 2015)

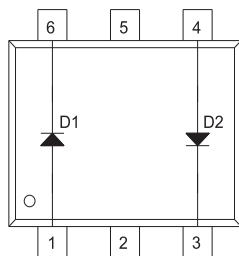
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SOT-563 CASE - MECHANICAL OUTLINE



PIN CONFIGURATION



LEAD CODE:

- 1) Anode D1
- 2) NC
- 3) Cathode D2
- 4) Anode D2
- 5) NC
- 6) Cathode D1

MARKING CODE: 63O

DIMENSIONS

SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.0027	0.007	0.07	0.18
B	0.008		0.20	
C	0.017	0.024	0.45	0.60
D	0.059	0.067	1.50	1.70
E	0.020		0.50	
F	0.059	0.067	1.50	1.70
G	0.043	0.051	1.10	1.30
H	0.006	0.012	0.15	0.30

SOT-563 (REV: R2)

R5 (15-June 2015)

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SERVICES

- Bonded Inventory
- Custom Electrical Screening
- Custom Electrical Characteristic Curves
- SPICE Models
- Custom Packaging
- Package Base Options
- Custom Device Development/ Multi Discrete Modules (MDM™)
- Bare Die Available for Hybrid Applications

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R5 (15-June 2015)